Substitute Form PTO-1449 (Modified)	U.S. Department of Commerce Patent and Trademark Office	Attorney's Docket No. 10559-879001	Application No. 10/688,306	OIR	12
1.7	closure Statement pplicant	Applicant Yan Borodovsky		MAR 3 1 ZOD	Soc
(Use several si	heets if necessary)	Filing Date October 17, 2003	Group Art Unit 2851	PAODAARK (S)	10 m

	U.S. Patent Documents										
Examiner Initial	Desig. ID	Document Number	Publication Date	Patentee	Class	Subclass	Filing Date If Appropriate				
	AA										
	AB				. [
	AC										
	AD			•							

	Foreign Patent Documents or Published Foreign Patent Applications											
Examiner	Desig.	Document	Publication	Country or			Trans	lation				
Initial	ID	Number	Date	Patent Office	Class	Subclass	Yes	No				
	AE	/										
	AB				•							
./	AG	- 1										

	Other D	ocuments (include Author, Title, Date, and Place of Publication)
Examiner	Desig.	
Initial	ID	Document
P4-	AH	M. Fritze, et al., "Gratings of regular arrays and trim exposures for ultralarge scale integrated circuit phase-shift lithography", J. of Vacuum Science & Technology B, 19(6):2366-2370, Nov/Dec 2001.
Rs	AI	J.A. Hoffnagle, et al., "Liquid immersion deep-ultraviolet interferometric lithography", J. of Vacuum Science & Technology B, 17(6):3306-3309, Nov/Dec 1999.
PA	AJ	Marc D. Levenson, et al., "Exposing the DUV SCAAM - 75 nm Imaging on the Cheap!", Proc. of SPIE: Design, Process Integration, and Characterization for Microelectronics, 4692:288-297, March 2002.
71	AK	Alex K. Raub, et al., "Deep UV immersion interferometric lithography", Proc. of SPIE: Optical Microlithography XVI, 5040:667-678, Feb. 2003.
722	AL	Bruce W. Smith, et al., "Water immersion optical lithography at 193 nm", J. Microlith., Microfab., Microsyst., 3(1):44-51, Jan. 2004.
21	AM	Akiyoshi Susuki, et al., "Multilevel imaging system realizing k ₁ +=0.3 lithography", <i>Proc. of SPIE:</i> Optical Microlithography XII, 3679:396-407, Mar. 1999.
P4	AN	M. Switkes, et al., "Extending optics to 50 nm and beyond with immersion lithography", J. of Vacuum Science & Technology B, 21(6):2794-2799, Nov/Dec 2003.
PA	AQ	Brian Tyrrell, et al., "Investigation of the physical and practical limits of dense-only phase shift lithography for circuit feature definition", J. Microlith., Microfab., Microsyst., 1(3):244-252, Oct. 2002.
PA	AP	Saleem H. Zaidi, et al., "Multiple exposure interferometric lithography", Proc. of SPIE: Optical Microlithography VII, 2197:869-875, Mar. 1994.
22	AQ	M. Fritze, et al., "Preprint of poster presentation entitled "High-Throughput Hybrid Optical Maskless Lithography: All-Optical 32-nm Node Imaging,", Presented at SPIE Microlithography 2005, San Jose, California, USA, March 3, 2005.

Examiner Signature	Date Considered
1/2	8/3/05
125.70	9, 7
EXAMINER: Initials citation considered. Draw line through citation if no	t in conformance and not considered. Include copy of this form with
next communication to applicant.	

	ubstitute Form PTO-1449 lodified)	U.S. Department Patent and Tra	t of Commerce	Attor 105	ney's Docket No. 59-879001	Application No. 10/688,306	
	Information Disc by Ap	losure Stateme	ht	Agg			··
(3	(Use several sh 7 CFR §1.98(b))	\	MAY 2 6 200		Date ober 17, 2003	Group Art Unit 2851	
			(1/2 maps)	:/		 	

	U.S. Patent Documents									
Examiner Initial	Desig. ID	Document Number	Publication Date	Patentee	Class	Subclass	Filing Date If Appropriate			
PA	AA	2005/0073671	04/2005	Borodovsky			,			
Dr	AB	2005/0074698	04/2005	Borodovsky			·			
82	AC	2005/0085085	04/2005	Borodovsky						
PA	AD	2005/0088633	04/2005	Borodovsky						
24	AE	5,759,744	06/1998	Brueck, et al.						
P	AF	6,233,044	05/2001	Brueck, et al.	_					
	AG									
	_ AH									
·	ΑĪ									
	AJ									
	AK									

	Foreig	n Patent Doc	uments or Pu	ıblished Foreign	Patent A	Application	ns	
Examiner	Desig.	Document	Publication	Country or		V	Trans	lation
Initial	ID	Number	Date	Patent Office	Class	Subclass	Yes	No .
	AL							
	AM							
	AN							
	AO							
	AP							

	Other D	ocuments (include Author, Title, Date, and Place of Publication)
Examiner Initial	Desig. ID	Document
	AQ	
	AR	
	AS	
	ΑT	

Examiner Signature (1)	Date Considered
	8/2/2
1-1 the	0/ 1/07
EVANINED: Initials situation persistened. Draw line through situation if	not in conformance and not considered. Include convent this form with
	iot in conformance and not considered. Include copy of this form with
EXAMINER: Initials citation considered. Draw line through citation if r	8/3/05

2851

Form PTO: 449

U.S. Department of Commerce Palent and Trademark Office
Information Disclosure Statement Substitute Form PTO (Modified) Attorney's Docket No. Application No. 10559-879001 10/688,306 **Applicant** by Applicant (Use several sheets if necessary) Yan Borodovsky Filing Date **Group Art Unit**

(37 CFR §1.98(b))

October 17, 2003

	U.S. Patent Documents										
Examiner Initial	Desig. ID	Document Number	Publication Date	Patentee	Class	Subclass	Filing Date If Appropriate				
Ph	AA	5,759,744	June 2, 1998	Brueck, et al.							
P1-	AB	5,415,835	May 16, 1995	Brueck, et al.							
P4	AC	5,328,807	July 12, 1994	Tanaka, et al.							
P	AD	6,553,562	April 22, 2003	Capodieci, et al.							
	AE										
	AF	•									
	AG										
	АН										
	AI										
	AJ										
	AK										

	Foreign Patent Documents or Published Foreign Patent Applications											
Examiner	Desig.	ig. Document	Publication	Country or			Translation					
Initial	ID	Number	Date	Patent Office	Class	Subclass	Yes	No				
37	AL	EP 0855623	July 29, 1998	EP								
P	_ AM	WO 98/32054	July 23, 1998	PCT								
	AN											
	AO			•								
	ΑP		•									

Other Documents (include Author, Title, Date, and Place of Publication)			
Examiner	Desig.		
Initial	ID	Document	
Pt-	AQ	Ishibashi, et al., "AFM Lithography Combined with Optical Lithography", IEEE Microprocesses and Nanotechnology Conference 2000, pp. 192-193 (July 2000).	
DJ	AR	Martin, et al., "Ordered Magnetic Nanostructures: Fabrication and Properties", J. Magnetism and Magnetic Materials, 256(1-3):449-501 (January 2003).	
	AS		
	AT		

Examiner Signature	Date Considered			
EXAMINER: Initials diation considered. Draw line through diation if not in conformance and not considered. Include copy of this form with next communication to applicant.				